HOSTAFORM® S 9244 XAP®2

High impact modified, low emission
POM copolymer, modified Injection molding type, elastomer-containing; with higher impact strength and slightly lower hardness, rigidity and chemical resistance than the basic type HOSTAFORM® C 9021 Reduced emission grade, Emission according to VDA 275 < 5 mg/kg good weld strength. Preliminary Datasheet

Rheological properties

Melt volume-flow rate	1.4	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	1.7	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.6	%	ISO 294-4, 2577

Typical mechanical properties

Tensile Modulus	1450	MPa	ISO 527-1/-2
Yield stress, 50mm/min	33	MPa	ISO 527-1/-2
Yield strain, 50mm/min	7	%	ISO 527-1/-2
Nominal strain at break	>50	%	ISO 527-1/-2
Flexural Modulus	1450	MPa	ISO 178
Tensile creep modulus, 1h	1200	MPa	ISO 899-1
Tensile creep modulus, 1000h	650	MPa	ISO 899-1
Charpy impact strength, 23°C	NB	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	200[P]	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	18	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	12	kJ/m^2	ISO 179/1eA

[P]: Partial Break

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	68	°C	ISO 75-1/-2
Vicat softening temperature, 50°C/h, 50N	115	°C	ISO 306
Coeff. of linear therm. expansion, parallel	130	E-6/K	ISO 11359-1/-2

Electrical properties

Relative permittivity, 100Hz	3.6		IEC 62631-2-1
Relative permittivity, 1MHz	3.6		IEC 62631-2-1
Dissipation factor, 100Hz	40	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	60	E-4	IEC 62631-2-1
Volume resistivity	1E11	Ohm.m	IEC 62631-3-1
Surface resistivity	1E13	Ohm	IEC 62631-3-2
Comparative tracking index	PLC 0	PLC	UL 746A

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Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	1.2	%	Sim. to ISO 62
Density	1260	kg/m³	ISO 1183

Injection

Drying Temperature	100 - 120	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	0.15	%
Screw tangential speed	0.2 - 0.21	m/s
Max. mould temperature	60 - 80	°C
Back pressure	2	MPa
Injection speed	slow-medium	

Characteristics

Additives	Release agent

Additional information

Injection molding	Above pressures, including back pressure, are given as specific or plastic pressures. The back pressure on Hostaform® and Celcon® POM materials should be as low as possible, just enough to remove air from the pellets during feeding.

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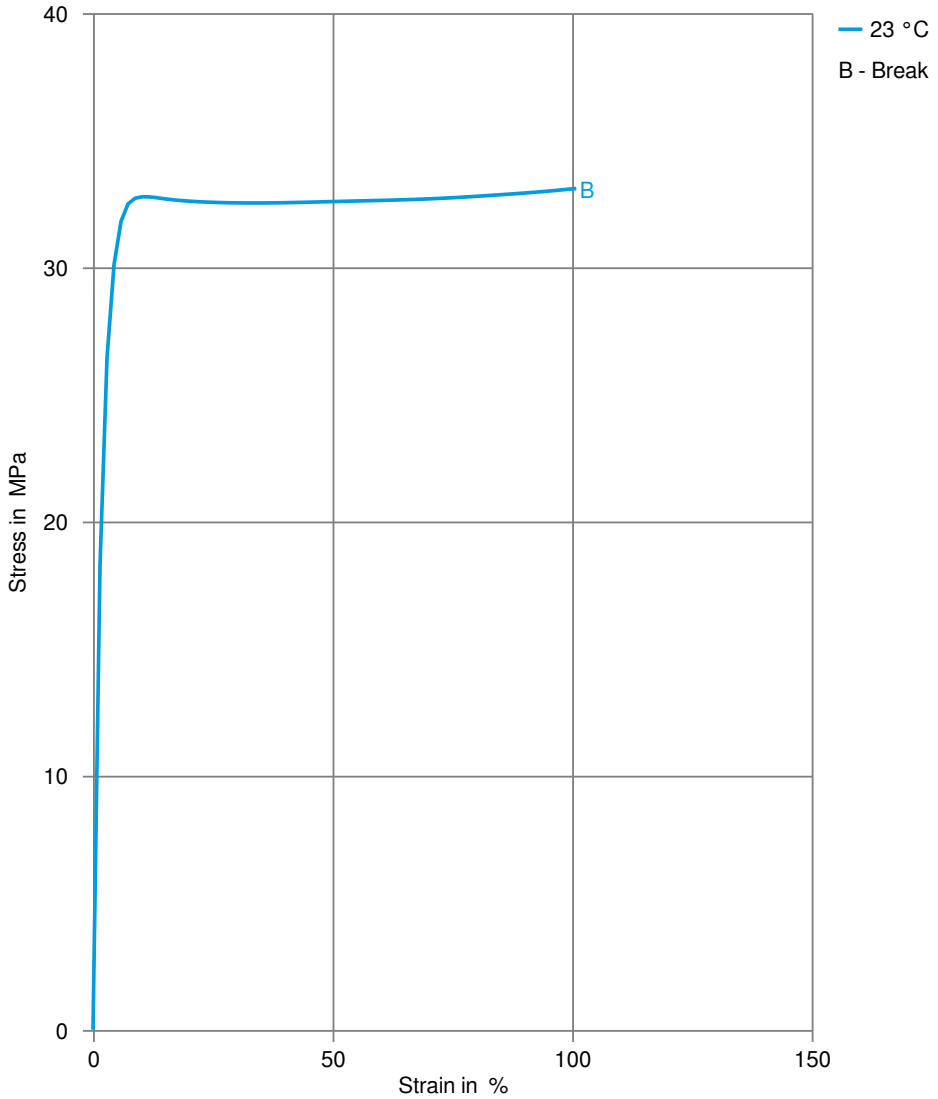
Stress-strain



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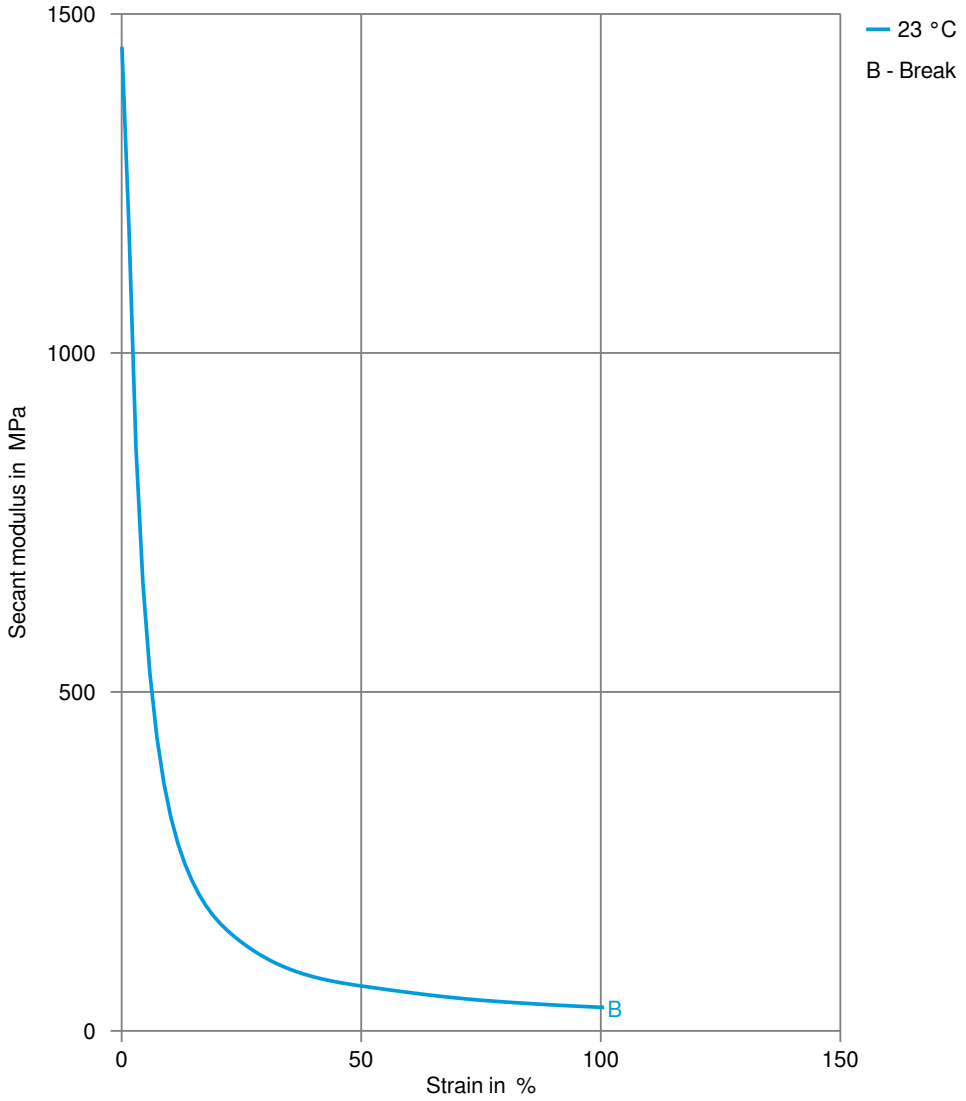
Secant modulus-strain



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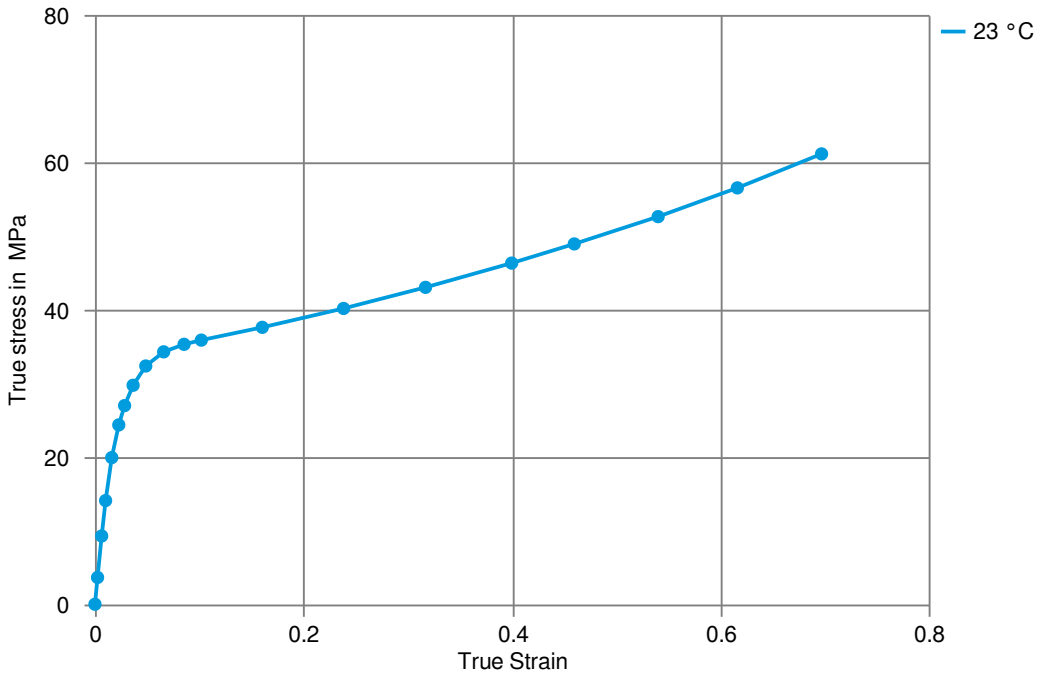
True stress-strain



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Processing Texts

Pre-drying	It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose
Longer pre-drying times/storage	The product can then be stored in standard conditions until processed.
Injection molding	Above pressures, including back pressure, are given as specific or plastic pressures. The back pressure on Hostaform® and Celcon® POM materials should be as low as possible, just enough to remove air from the pellets during feeding.

Other Approvals

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OEM	Specification	Additional Information
Mercedes-Benz Group (Daimler)	DBL 5404	BQF
Renault	UB15	